

Title (en)  
Raised microstructures

Title (de)  
Erhobene Mikrostrukturen

Title (fr)  
Microstructures en relief

Publication  
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Application  
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Abstract (en)  
[origin: WO0215636A2] Multiple embodiments of solid state micro-structures, such as a condenser microphone, are disclosed. According to one embodiment, the transducer a fixed perforated member, a freely movable diaphragm spaced from the perforated member, a support ring in the perforated member maintaining the proper spacing between the diaphragm and the perforated member near the perimeter; and compliant suspension springs allowing the diaphragm to rest freely on the support ring and yet mechanically decouples the diaphragm from the perforated member. According to another embodiment, a raised micro-structure is disclosed for use in a silicon based device. The raised micro-structure comprises a generally planar film having a ribbed sidewall supporting the film.

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Citation (search report)  
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